

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ZHAOXU SHEN	11/28/2017
JIANHUA JU	11/28/2017
SHAOFENG YU	11/28/2017
YANG LIU	11/27/2017
YONGMENG LEE	11/27/2017

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION
Street Address:	18 WENCHANG ROAD
Internal Address:	BEIJING ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA
City:	BEIJING
State/Country:	CHINA
Postal Code:	100176
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
Street Address:	18 ZHANGJIANG ROAD, PUDONG NEW AREA
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201203

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15824776

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	SMIC00114 US
NAME OF SUBMITTER:	JING ZHENG, REG. NO. 75,830
SIGNATURE:	/Jing Zheng/
DATE SIGNED:	11/28/2017

Total Attachments: 3

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ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Zhaoxu SHEN	of	18 Zhangjiang Road Pudong New Area Shanghai, P.R.C. 201203
Jianhua JU	of	18 Zhangjiang Road Pudong New Area Shanghai, P.R.C. 201203
Shaofeng YU	of	18 Zhangjiang Road Pudong New Area Shanghai, P.R.C. 201203
Yang LIU	of	18 Zhangjiang Road Pudong New Area Shanghai, P.R.C. 201203
YongMeng LEE	of	18 Zhangjiang Road Pudong New Area Shanghai, P.R.C. 201203

hereby sell, assign and transfer to **Semiconductor Manufacturing International (Beijing) Corporation**, having a place of business at 18 Wenchang Road, Beijing Economic-Technological Development Area, Beijing, China, 100176, and, to **Semiconductor Manufacturing International (Shanghai) Corporation**, having a place of business at 18 Zhangjiang Road, Pudong New Area, Shanghai, P.R.C. 201203 its successors and assigns, the entire right, title and interest throughout the world in the invention entitled

A SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisionals, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

CLIENT REFERENCE NO.: 2015-02362-SH-US
ATTORNEY DOCKET NO.: SMIC00114 US

Executed this 28th day of November, 2017.

Zhaoxu SHEN

Zhaoxu SHEN

WITNESSED:

Helili

Signature

何丽莉

Date

2017-11-28

Type or print name of witness

Executed this 28th day of November, 2017.

Jianhua JU

Jianhua JU

WITNESSED:

Helili

Signature

何丽莉

Date

2017-11-28

Type or print name of witness

Executed this 28th day of November, 2017.

Shaofeng YU

Shaofeng YU

WITNESSED:

Helili

Signature

何丽莉

Date

2017-11-28

Type or print name of witness

Executed this 27th day of November, 2017.

Liu, Yang
Yang LIU

WITNESSED:

Helili

Signature

何丽莉

Date

2017-11-28

Type or print name of witness

Executed this 27th day of November, 2017.

YongMeng LEE
YongMeng LEE

WITNESSED:

Helili

Signature

何丽莉

Date

2017-11-28

Type or print name of witness